

Final Product Change Notification

202211043F01 : C90 LQFP100 14*14 Products Assembly Site Expansion to TFME-T

Note: This notice is NXP Company Proprietary.

Issue Date: Dec 15, 2022 Effective date: Mar 15, 2023

Here is your personalized notification about a NXP general announcement. For detailed information we invite you to view this notification online Change Category

Change Category

[]Wafer Fab Process	[]Assembly Process	[X]Product Marking	[]Test Process	[]Design
[]Wafer Fab Materials	[X]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
[]Wafer Fab Location	[X]Assembly Location	[]Packing/Shipping/Labeling	[]Test Location	[]Electrical spec./Test coverage
F 1	F 100			

[]Firmware []Other

PCN Overview Description

NXP Semiconductors is announcing the assembly site expansion for the C90 LQFP100 14*14 packages from current TongFu Microeletronics Co.,Ltd, Nantong. China (TFME) to Tongfu Tongke (Nantong) Microelectronics Co.,LTD (TFME-T). Assembly site expansion was successfully qualified adhering to NXP specifications. Please see the attached file(s) for additional details and contact your NXP sales or marketing representative for additional information.

Reason

Qualification of the TFME-T assembly Facility is to ensure manufacturing flexibility and customer supply assurance.

Identification of Affected Products

Top Side Marking The first one/two characters of the third line will indicate assembly site: XN=TFME VX=TFME-T Product Availability

Product Availability

Sample Information Samples are available fromNov 29, 2022 Sample Part Number: PKV58F1M0VLL24, PK60DN512ZVLL10 Original Part Number: MKV58F1M0VLL24, MK60DN512ZVLL10

For other samples, NXP will provide upon customer's request, or customer contact Sales/Marketer. **Production**

Planned first shipmentApr 09, 2023

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality **Disposition of Old Products** Site Expansion, no inventory depletion is needed. **Additional information**

Self qualification:<u>view online</u> Additional documents: <u>view online</u> **Timing and Logistics**

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jan 14, 2023.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Linda Zhang

Position Product Engineer

e-mail address <u>yanling.zhang@nxp.com</u>

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

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